

Optoelectronic Components Catalog

World Class Products - Light Sensing Solutions

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UDT Sensors, Inc. has expanded business operations to merge with AME, Centrovision, Ferson Technologies and OSI Fibercomm; the combined infrastructure will now be known as **OSI Optoelectronics, Inc.**

The new OSI Optoelectronics, Inc., will continue to put forth extensive engineering solutions aligned with efficient manufacturing. In addition, with our growing base of customer support we will expand into new product arenas and application domains. OSI Optoelectronics, Inc. will carry on these market-driven spirits in being the largest and most counted on manufacturer of optical sensors.

In today's ever-competitive industry that views success as synonymous with efficient process, OSI Optoelectronics, Inc. U.S. headquarters is housed in a modern 54,000 sq.ft. facility. Additionally, it operates two world-class manufacturing facilities overseas in both India and Malaysia for meeting high-volume production requirements. And our innovative vertical integrations, along with well-established global sales roots in both Europe and U.S. alike, help reduce design cycle-time and keep implementation cost to a minimum for our customers.

COMPREHENSIVE solutions:

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X-Ray Products (CT Scanner, Security System and Industrial Inspection Apparatus)

Opto-assembly (Optical Switch, LED and Cable Assembly)

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Tele-com and Data-com Applications (SONET/SDH Application and Fiber-coupled Assembly)

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Production Tooling / Machining

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GMP-compliant Practices

Value-added Assemblies (Heat Staking and Ultrasonic Welding)

Custom Tooling (Computer Peripherals and Medical Electronics)

OSI Optoelectronics, Inc. commitments:

Customer

Innovation

Excellence in Service, Quality and Delivery

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ISO 9001 Certified

SO 13485 Certified

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Compliant to MIL-PRF-19500

Test and Environmental Test Capabilities compliant to MIL-TD-883 and MIL-STD-750

In-House J-STD-001C soldering instructor

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ISO 13485 Certified

ISO 140001 Certified

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Photodiode Characteristics and Applications

Silicon photodiodes are semiconductor devices responsive to high-energy particles and photons. Photodiodes operate by absorption of photons or charged particles and generate a flow of current in an external circuit, proportional to the incident power.

Photodiodes can be used to detect the presence or absence of minute quantities of light and can be calibrated for extremely accurate measurements from intensities below 1 pW/cm² to intensities above 100 mW/cm².

Silicon photodiodes are utilized in such diverse applications as :

- Spectroscopy
- Photography
- Analytical instrumentation
- Optical position sensors
- Beam alignment
- Surface characterization
- Laser range finders
- Optical communications
- Medical imaging instruments

PLANAR DIFFUSED SILICON PHOTODIODE CONSTRUCTION

Planar diffused silicon photodiodes are simply P-N junction diodes. A P-N junction can be formed by diffusing either a P-type impurity (anode), such as Boron, into a N-type bulk silicon wafer, or a N-type impurity, such as Phosphorous, into a P-type bulk silicon wafer. The diffused area defines the photodiode active area. To form an ohmic contact another impurity diffusion into the backside of the wafer is necessary. The impurity is an N-type for P-type active area and P-type for an N-type active area. The contact pads are deposited on the front active area on defined areas, and on the backside, completely covering the device. The active area is then passivated with an anti-reflection coating to reduce the reflection of the light for a specific predefined wavelength. The non-active area on the top is covered with a thick layer of silicon oxide. By controlling the thickness of bulk substrate, the speed and responsivity of the photodiode can be controlled. Note that the photodiodes, when biased, must be operated in the reverse bias mode, i.e. a negative voltage applied to anode and positive voltage to cathode.

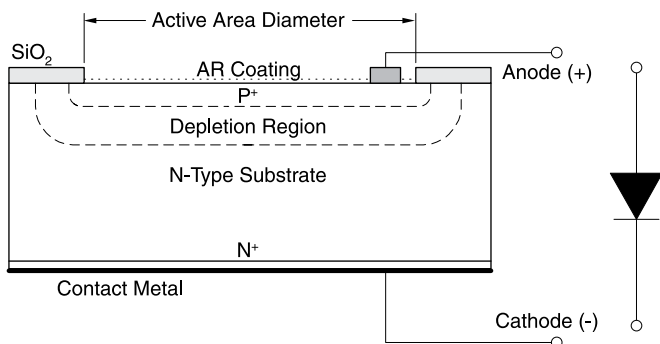


Figure 1. Planar diffused silicon photodiode

PRINCIPLE OF OPERATION

Silicon is a semiconductor with a band gap energy of 1.12 eV at room temperature. This is the gap between the valence band and the conduction band. At absolute zero temperature the valence band is completely filled and the conduction band is vacant. As the temperature increases, the electrons become excited and escalate from the valence band to the conduction band by thermal energy. The electrons can also be escalated to the conduction band by particles or photons with energies greater than 1.12eV, which corresponds to wavelengths shorter than 1100 nm. The resulting electrons in the conduction band are free to conduct current.

Due to concentration gradient, the diffusion of electrons from the N-type region to the P-type region and the diffusion of holes from the P-type region to the N-type region, develops a built-in voltage across the junction. The inter-diffusion of electrons and holes between the N and P regions across the junction results in a region with no free carriers. This is the depletion region. The built-in voltage across the depletion region results in an electric field with maximum at the junction and no field outside of the depletion region. Any applied reverse bias adds to the built in voltage and results in a wider depletion region. The electron-hole pairs generated by light are swept away by drift in the depletion region and are collected by diffusion from the undepleted region. The current generated is proportional to the incident light or radiation power. The light is absorbed exponentially with distance and is proportional to the absorption coefficient. The absorption coefficient is very high for shorter wavelengths in the UV region and is small for longer wavelengths (Figure 2). Hence, short wavelength photons such as UV, are absorbed in a thin top surface layer while silicon becomes transparent to light wavelengths longer than 1200 nm. Moreover, photons with energies smaller than the band gap are not absorbed at all.

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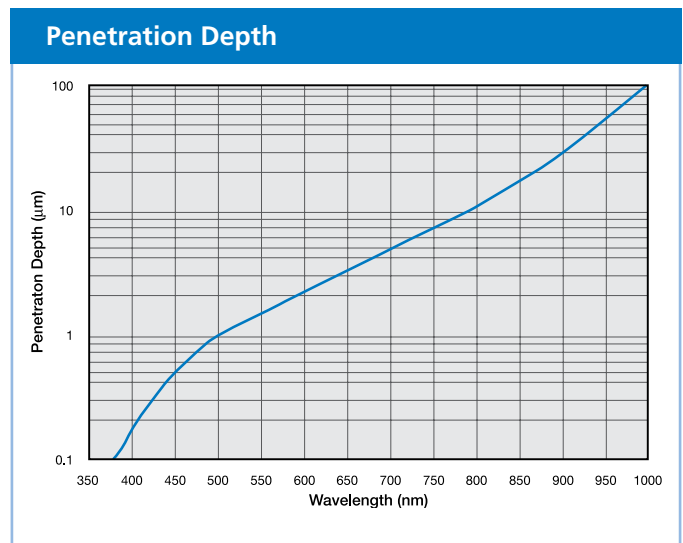


Figure 2. Penetration depth (1/e) of light into silicon substrate for various wavelengths.

ELECTRICAL CHARACTERISTICS

A silicon photodiode can be represented by a current source in parallel with an ideal diode (Figure. 3). The current source represents the current generated by the incident radiation, and the diode represents the p-n junction. In addition, a **junction capacitance** (C_j) and a **shunt resistance** (R_{sh}) are in parallel with the other components. **Series resistance** (R_s) is connected in series with all components in this model.

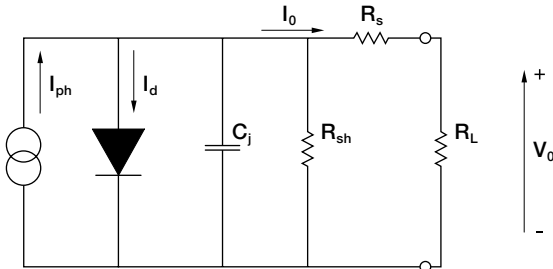


Figure 3. Equivalent Circuit for the silicon photodiode

Shunt Resistance, R_{sh}

Shunt resistance is the slope of the current-voltage curve of the photodiode at the origin, i.e. $V=0$. Although an ideal photodiode should have an infinite shunt resistance, actual values range from 10's to 1000's of Mega ohms. Experimentally it is obtained by applying ± 10 mV, measuring the current and calculating the resistance. Shunt resistance is used to determine the noise current in the photodiode with no bias (photovoltaic mode). For best photodiode performance the highest shunt resistance is desired.

Series Resistance, R_s

Series resistance of a photodiode arises from the resistance of the contacts and the resistance of the undepleted silicon (Figure 1). It is given by:

$$R_s = \frac{(W_s - W_d)\rho}{A} + R_c \quad (1)$$

Where W_s is the thickness of the substrate, W_d is the width of the depleted region, A is the diffused area of the junction, ρ is the resistivity of the substrate and R_c is the contact resistance. Series resistance is used to determine the linearity of the photodiode in photovoltaic mode (no bias, $V=0$). Although an ideal photodiode should have no series resistance, typical values ranging from 10 to 1000 Ω 's are measured.

Junction Capacitance, C_j

The boundaries of the depletion region act as the plates of a parallel plate capacitor (Figure 1). The junction capacitance is directly proportional to the diffused area and inversely proportional to the width of the depletion region. In addition, higher resistivity substrates have lower junction capacitance. Furthermore, the capacitance is dependent on the reverse bias as follows:

$$\begin{aligned} C_j &= \frac{\epsilon_{si}\epsilon_0 A}{\sqrt{2\epsilon_{si}\epsilon_0\mu\rho(V_A + V_{bi})}} \quad (2) \\ &= A\sqrt{\frac{\epsilon_{si}\epsilon_0}{2\mu\rho(V_A + V_{bi})}} \\ &= \frac{\epsilon_{si}\epsilon_0 A}{W_d} \end{aligned}$$

$$\text{Depletion Depth } W_d = \sqrt{2\epsilon_{si}\epsilon_0\mu\rho(V_A + V_{bi})}$$

Typical Capacitance vs. Reverse Bias

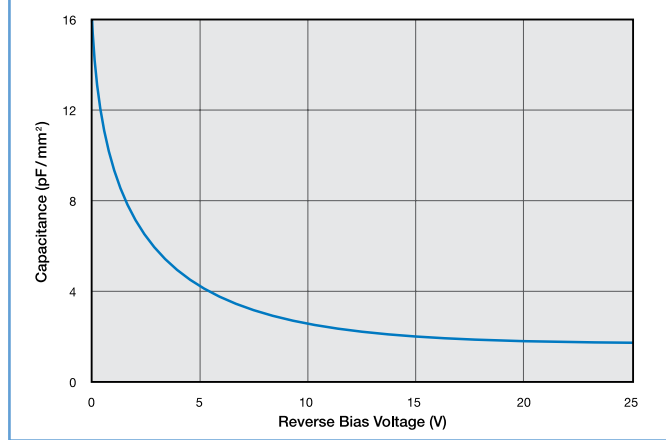


Figure 4. Capacitance of Photoconductive Devices versus Reverse Bias Voltage

where $\epsilon_0 = 8.854 \times 10^{-14}$ F/cm, is the permittivity of free space, $\epsilon_{si} = 11.9$ is the silicon dielectric constant, $\mu = 1400$ cm²/Vs is the mobility of the electrons at 300 K, ρ is the resistivity of the silicon, V_{bi} is the built-in voltage of silicon and V_A is the applied bias. Figure 4 shows the dependence of the capacitance on the applied reverse bias voltage. Junction capacitance is used to determine the speed of the response of the photodiode.

Rise / Fall Time and Frequency Response, t_r / t_f / f_{3dB}

The rise time and fall time of a photodiode is defined as the time for the signal to rise or fall from 10% to 90% or 90% to 10% of the final value respectively. This parameter can be also expressed as frequency response, which is the frequency at which the photodiode output decreases by 3dB. It is roughly approximated by:

$$t_r \cong \frac{0.35}{f_{3dB}} \quad (3)$$

There are three factors defining the response time of a photodiode:

1. t_{DRIFT} , the charge collection time of the carriers in the depleted region of the photodiode.
2. $t_{DIFFUSED}$, the charge collection time of the carriers in the undepleted region of the photodiode.
3. t_{RC} , the RC time constant of the diode-circuit combination.

t_{RC} is determined by $t_{RC} = 2.2 RC$, where R , is the sum of the diode series resistance and the load resistance ($R_s + R_L$), and C , is the sum of the photodiode junction and the stray capacitances ($C_j + C_s$). Since the junction capacitance (C_j) is dependent on the diffused area of the photodiode and the applied reverse bias (Equation 2), faster rise times are obtained with smaller diffused area photodiodes, and larger applied reverse biases. In addition, stray capacitance can be minimized by using short leads, and careful lay-out of the electronic components. The total rise time is determined by:

$$t_R = \sqrt{t_{DRIFT}^2 + t_{DIFFUSED}^2 + t_{RC}^2} \quad (4)$$

Generally, in photovoltaic mode of operation (no bias), rise time is dominated by the diffusion time for diffused areas less than 5 mm² and by RC time constant for larger diffused areas for all wavelengths. When operated in photoconductive mode (applied reverse bias), if the photodiode is fully depleted, such as high speed series, the dominant factor is the drift time. In non-fully depleted photodiodes, however, all three factors contribute to the response time.

Photodiode Characteristics

OPTICAL CHARACTERISTICS

Responsivity, R_λ

The responsivity of a silicon photodiode is a measure of the sensitivity to light, and it is defined as the ratio of the photocurrent I_p to the incident light power P at a given wavelength:

$$R_\lambda = \frac{I_p}{P} \quad (5)$$

In other words, it is a measure of the effectiveness of the conversion of the light power into electrical current. It varies with the wavelength of the incident light (Figure 5) as well as applied reverse bias and temperature.

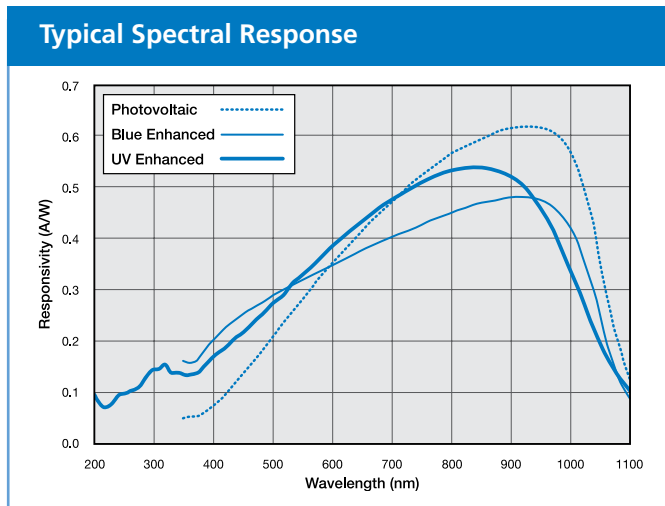


Figure 5. Typical Spectral Responsivity of Several Different Types of Planar Diffused Photodiodes

Responsivity increases slightly with applied reverse bias due to improved charge collection efficiency in the photodiode. Also there are responsivity variations due to change in temperature as shown in figure 6. This is due to decrease or increase of the band gap, because of increase or decrease in the temperature respectively. Spectral responsivity may vary from lot to lot and it is dependent on wavelength. However, the relative variations in responsivity can be reduced to less than 1% on a selected basis.

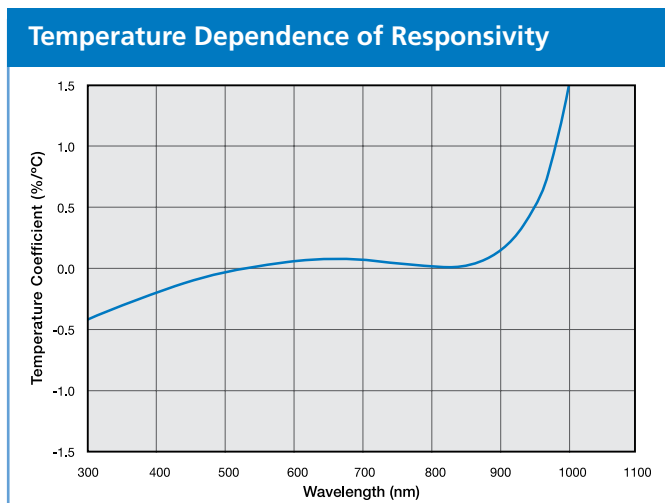


Figure 6. Typical Temperature Coefficient of Responsivity For Silicon Photodiode

Quantum Efficiency, Q.E.

Quantum efficiency is defined as the fraction of the incident photons that contribute to photocurrent. It is related to responsivity by:

$$\begin{aligned} Q.E. &= \frac{R_{\lambda \text{ Observed}}}{R_{\lambda \text{ Ideal}}} \\ &= R_{\lambda} \frac{hc}{\lambda q} \\ &= 1240 \frac{R_{\lambda}}{\lambda} \end{aligned} \quad (6)$$

where $h=6.63 \times 10^{-34}$ J-s, is the Planck constant, $c=3 \times 10^8$ m/s, is the speed of light, $q=1.6 \times 10^{-19}$ C, is the electron charge, R_λ is the responsivity in A/W and λ is the wavelength in nm.

Non-Uniformity

Non-Uniformity of response is defined as variations of responsivity observed over the surface of the photodiode active area with a small spot of light. Non-uniformity is inversely proportional to spot size, i.e. larger non-uniformity for smaller spot size.

Non-Linearity

A silicon photodiode is considered linear if the generated photocurrent increases linearly with the incident light power. Photocurrent linearity is determined by measuring the small change in photocurrent as a result of a small change in the incident light power as a function of total photocurrent or incident light power. Non-Linearity is the variation of the ratio of the change in photocurrent to the same change in light power, i.e. $\Delta I/\Delta P$. In another words, linearity exhibits the consistency of responsivity over a range of light power. Non-linearity of less than $\pm 1\%$ are specified over 6-9 decades for planar diffused photodiodes. The lower limit of the photocurrent linearity is determined by the noise current and the upper limit by the series resistance and the load resistance. As the photocurrent increases, first the non-linearity sets in, gradually increasing with increasing photocurrent, and finally at saturation level, the photocurrent remains constant with increasing incident light power. In general, the change in photocurrent generated for the same change in incident light power, is smaller at higher current levels, when the photodetector exhibits non-linearity. The linearity range can slightly be extended by applying a reverse bias to the photodiode.

(continued)

I-V CHARACTERISTICS

The current-voltage characteristic of a photodiode with no incident light is similar to a rectifying diode. When the photodiode is forward biased, there is an exponential increase in the current. When a reverse bias is applied, a small reverse saturation current appears. It is related to dark current as:

$$I_D = I_{SAT} (e^{\frac{qV_A}{k_B T}} - 1) \quad (7)$$

where I_D is the photodiode dark current, I_{SAT} is the reverse saturation current, q is the electron charge, V_A is the applied bias voltage, $k_B = 1.38 \times 10^{-23}$ J / K, is the Boltzmann Constant and T is the absolute temperature (273 K = 0 °C).

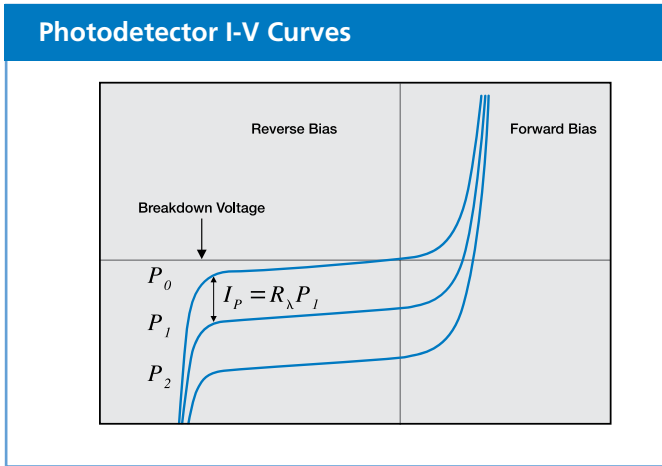


Figure 7. Characteristic I-V Curves of an OSI Optoelectronics photodiode for Photoconductive and Photovoltaic modes of operation. P_0 - P_2 represent different light levels.

This relationship is shown in figure 7. From equation 7, three various states can be defined:

- $V = 0$, In this state, the dark current $I_p = 0$.
- $V = +V$, In this state the current increases exponentially. This state is also known as forward bias mode.
- $V = -V$, When a very large reverse bias is applied to the photodiode, the dark current becomes the reverse saturation current, I_{SAT} .

Illuminating the photodiode with optical radiation, shifts the I-V curve by the amount of photocurrent (I_p). Thus:

$$I_{TOTAL} = I_{SAT} (e^{\frac{qV_A}{k_B T}} - 1) - I_p \quad (8)$$

where I_p is defined as the photocurrent in equation 5.

As the applied reverse bias increases, there is a sharp increase in the photodiode current. The applied reverse bias at this point is referred to as breakdown voltage. This is the maximum applied reverse bias, below which, the photodiode should be operated (also known as maximum reverse voltage). Breakdown voltage, varies from one photodiode to another and is usually measured, for small active areas, at a dark current of 10 μ A.

NOISE

In a photodiode, two sources of noise can be identified; Shot noise and Johnson noise:

Shot Noise

Shot noise is related to the statistical fluctuation in both the photocurrent and the dark current. The magnitude of the shot noise is expressed as the root mean square (rms) noise current:

$$I_{sn} = \sqrt{2q(I_p + I_D)\Delta f} \quad (9)$$

Where $q = 1.6 \times 10^{-19}$ C, is the electron charge, I_p is the photogenerated current, I_D is the photodetector dark current and Δf is the noise measurement bandwidth. Shot noise is the dominating source when operating in photoconductive (biased) mode.

Thermal or Johnson Noise

The shunt resistance in a photodetector has a Johnson noise associated with it. This is due to the thermal generation of carriers. The magnitude of this generated noise current is:

$$I_{jn} = \sqrt{\frac{4k_B T \Delta f}{R_{SH}}} \quad (10)$$

Where $k_B = 1.38 \times 10^{-23}$ J/K, is the Boltzmann Constant, T , is the absolute temperature in degrees Kelvin (273 K = 0 °C), Δf is the noise measurement bandwidth and R_{SH} , is the shunt resistance of the photodiode. This type of noise is the dominant current noise in photovoltaic (unbiased) operation mode.

Note: All resistors have a Johnson noise associated with them, including the load resistor. This additional noise current is large and adds to the Johnson noise current caused by the photodetector shunt resistance.

Total Noise

The total noise current generated in a photodetector is determined by:

$$I_{tn} = \sqrt{I_{sn}^2 + I_{jn}^2} \quad (11)$$

Noise Equivalent Power (NEP)

Noise Equivalent Power is the amount of incident light power on a photodetector, which generates a photocurrent equal to the noise current. NEP is defined as:

$$NEP = \frac{I_{tn}}{R_\lambda} \quad (12)$$

Where R_λ is the responsivity in A/W and I_{tn} is the total noise of the photodetector. NEP values can vary from 10^{-11} W/ $\sqrt{\text{Hz}}$ for large active area photodiodes down to 10^{-15} W/ $\sqrt{\text{Hz}}$ for small active area photodiodes.

(continued)

Photodiode Characteristics

TEMPERATURE EFFECTS

All photodiode characteristics are affected by changes in temperature. They include shunt resistance, dark current, breakdown voltage, responsivity and to a lesser extent other parameters such as junction capacitance.

Shunt Resistance and Dark Current:

There are two major currents in a photodiode contributing to dark current and shunt resistance. Diffusion current is the dominating factor in a photovoltaic (unbiased) mode of operation, which determines the shunt resistance. It varies as the square of the temperature. In photoconductive mode (reverse biased), however, the drift current becomes the dominant current (dark current) and varies directly with temperature. Thus, change in temperature affects the photodetector more in photovoltaic mode than in photoconductive mode of operation.

In photoconductive mode the dark current may approximately double for every 10 °C increase change in temperature. And in photovoltaic mode, shunt resistance may approximately double for every 6 °C decrease in temperature. The exact change is dependent on additional parameters such as the applied reverse bias, resistivity of the substrate as well as the thickness of the substrate.

Breakdown Voltage:

For small active area devices, by definition breakdown voltage is defined as the voltage at which the dark current becomes 10µA. Since dark current increases with temperature, therefore, breakdown voltage decreases similarly with increase in temperature.

Responsivity:

Effects of temperature on responsivity is discussed in the “Responsivity” section of these notes.

BIASING

A photodiode signal can be measured as a voltage or a current. Current measurement demonstrates far better linearity, offset, and bandwidth performance. The generated photocurrent is proportional to the incident light power and it must be converted to voltage using a transimpedance configuration. The photodiode can be operated with or without an applied reverse bias depending on the application specific requirements. They are referred to as “Photoconductive” (biased) and “Photovoltaic” (unbiased) modes.

Photoconductive Mode (PC)

Application of a reverse bias (i.e. cathode positive, anode negative) can greatly improve the speed of response and linearity of the devices. This is due to increase in the depletion region width and consequently decrease in junction capacitance. Applying a reverse bias, however, will increase the dark and noise currents. An example of low light level / high-speed response operated in photoconductive mode is shown in figure 8.

In this configuration the detector is biased to reduce junction capacitance thus reducing noise and rise time (t_r). A two stage amplification is used in this example since a high gain with a wide bandwidth is required. The two stages include a transimpedance pre-amp for current- to-voltage conversion and a non-inverting amplifier for voltage amplification. Gain and bandwidth (f_{3dB Max}) are directly determined by R_F, per equations (13) and (14). The gain of the second stage is approximated by 1 + R₁ / R₂. A feedback capacitor (C_F) will limit the frequency response and avoids gain peaking.

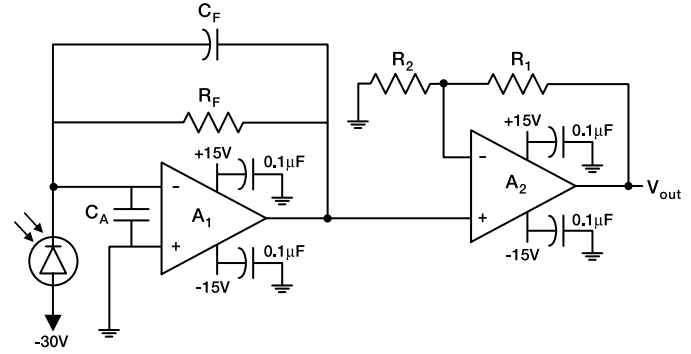


Figure 8. Photoconductive mode of operation circuit example: Low Light Level / Wide Bandwidth

$$f_{3dB Max} [Hz] = \sqrt{\frac{GBP}{2\pi R_F (C_J + C_F + C_A)}} \quad (13)$$

Where GBP is the Gain Bandwidth Product of amplifier (A₁) and C_A is the amplifier input capacitance.

$$Gain(V/W) = \frac{V_{OUT}}{P} = R_F \left(1 + \frac{R_1}{R_2}\right) R_A \quad (14)$$

In low speed applications, a large gain, e.g. >10MΩ can be achieved by introducing a large value (R_F) without the need for the second stage.

Typical components used in this configuration are:

Amplifier :	OPA-637, OPA-846, OPA-847, or similar
R _F :	1 to 10 KΩ Typical, depending on C _j
R ₁ :	10 to 50 kΩ
R ₂ :	0.5 to 10 kΩ
C _F :	0.2 to 2 pF

In high speed, high light level measurements, however, a different approach is preferred. The most common example is pulse width measurements of short pulse gas lasers, solid state laser diodes, or any other similar short pulse light source. The photodiode output can be either directly connected to an oscilloscope (Figure 9) or fed to a fast response amplifier. When using an oscilloscope, the bandwidth of the scope can be adjusted to the pulse width of the light source for maximum signal to noise ratio. In this application the bias voltage is large. Two opposing protection diodes should be connected to the input of the oscilloscope across the input and ground.

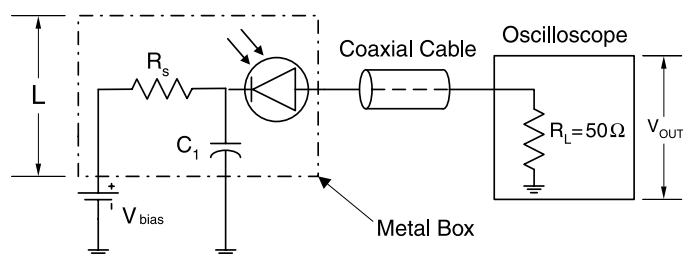


Figure 9. Photoconductive mode of operation circuit example: High Light Level / High Speed Response

(continued)

To avoid ringing in the output signal, the cable between the detector and the oscilloscope should be short (i.e. < 20cm) and terminated with a 50 ohm load resistor (R_L). The photodiode should be enclosed in a metallic box, if possible, with short leads between the detector and the capacitor, and between the detector and the coaxial cable. The metallic box should be tied through a capacitor (C_1), with lead length (L) less than 2 cm, where $R_L C_1 > 10 \tau$ (τ is the pulse width in seconds). R_S is chosen such that $R_S < V_{BIAS} / 10 I_{PDC}$, where I_{PDC} is the DC photocurrent. Bandwidth is defined as $0.35 / \tau$. A minimum of 10V reverse bias is necessary for this application. Note that a bias larger than the photodiode maximum reverse voltage should not be applied.

Photovoltaic Mode (PV)

The photovoltaic mode of operation (unbiased) is preferred when a photodiode is used in low frequency applications (up to 350 kHz) as well as ultra low light level applications. In addition to offering a simple operational configuration, the photocurrents in this mode have less variations in responsivity with temperature. An example of an ultra low light level / low speed is shown in figure 10.

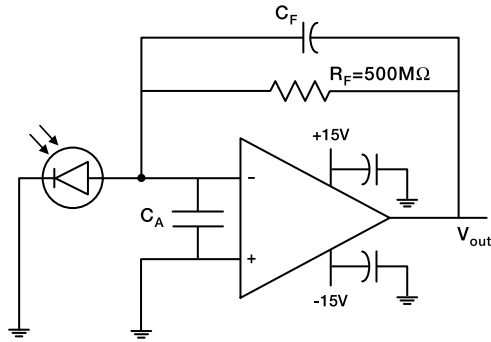


Figure 10. Photovoltaic mode of operation circuit example: Ultra low level light / low speed

In this example, a FET input operational amplifier as well as a large resistance feedback resistor (R_F) is considered. The detector is unbiased to eliminate any additional noise current. The total output is determined by equation (15) and the op-amp noise current is determined by R_F in equation (16):

$$V_{OUT} = I_P \times R_F \quad (15)$$

$$I_N \left[\frac{A_{rms}}{\sqrt{Hz}} \right] = \sqrt{\frac{4kT}{R_F}} \quad (16)$$

where $k=1.38 \times 10^{-23}$ J/K and T is temperature in K.

For stability, select C_F such that

$$\sqrt{\frac{GBP}{2\pi R_F (C_J + C_F + C_A)}} > \frac{1}{2\pi R_F C_F} \quad (17)$$

Operating bandwidth, after gain peaking compensation is:

$$f_{OP} [Hz] = \frac{1}{2\pi R_F C_F} \quad (18)$$

Some recommended components for this configuration are:

Amplifier :	OPA111, OPA124, OPA627 or similar
R_F :	500 MΩ

These examples or any other configurations for single photodiodes can be applied to any of OSI Optoelectronics' monolithic, common substrate liner array photodiodes. The output of the first stage pre-amplifiers can be connected to a sample and hold circuit and a multiplexer. Figure 11 shows the block diagram for such configuration.

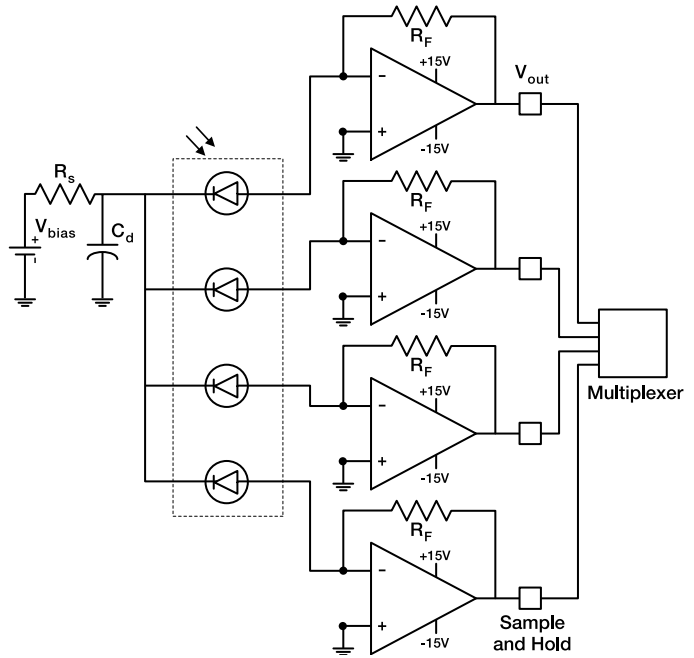


Figure 11. Circuit example for a multi-element, common cathode array

POSITION SENSING DETECTORS

Silicon photodetectors are commonly used for light power measurements in a wide range of applications such as;

- Bar-code readers,
- Laser printers,
- Medical imaging,
- Spectroscopy and more.

There is another function, however, which utilizes the photodetectors as optical position sensors. They are widely referred to as **Position Sensing Detectors or simply PSD's**. The applications vary from human eye movement monitoring, 3-D modeling of human motion to laser, light source, and mirrors alignment. They are also widely used in ultra-fast, accurate auto focusing schemes for a variety of optical systems, such as microscopes, machine tool alignment, vibration analysis and more. The position of a beam within fractions of microns can be obtained using PSD's. They are divided into two families: **segmented PSD's** and **lateral effect PSD's**.

Segmented PSD's

Segmented PSD's, are common substrate photodiodes divided into either two or four segments (for one or two-dimensional measurements, respectively), separated by a gap or dead region. A symmetrical optical beam generates equal photocurrents in all segments, if positioned at the center. The relative position is obtained by simply measuring the output current of each segment. They offer position resolution better than 0.1 μm and accuracy higher than lateral effect PSD's due to superior responsivity match between the elements. Since the position resolution is not dependent on the S/N of the system, as it is in lateral effect PSD's, very low light level detection is possible. They exhibit excellent stability over time and temperature and fast response times necessary for pulsed applications. They are however, confined to certain limitations, such as the light spot has to overlap all segments at all times and it can not be smaller than the gap between the segments. It is important to have a uniform intensity distribution of the light spot for correct measurements. They are excellent devices for applications like nulling and beam centering.

Lateral Effect PSD's

Lateral effect PSD's, are continuous single element planar diffused photodiodes with no gaps or dead areas. These types of PSD's provide direct readout of a light spot displacement across the entire active area. This is achieved by providing an analog output directly proportional to both the position and intensity of a light spot present on the detector active area. A light spot present on the active area will generate a photocurrent, which flows from the point of incidence through the resistive layer to the contacts. This photocurrent is inversely proportional to the resistance between the incident light spot and the contact. When the input light spot is exactly at the device center, equal current signals are generated. By moving the light spot over the active area, the amount of current generated at the contacts will determine the exact light spot position at each instant of time. These electrical signals are proportionately related to the light spot position from the center.

The main advantage of lateral-effect diodes is their wide dynamic range. They can measure the light spot position all the way to the edge of the sensor. They are also independent of the light spot profile and intensity distribution that effects the position reading in the segmented diodes. The input light beam may be any size and shape, since the position of the centroid of the light spot is indicated and provides electrical output signals proportional to the displacement from the center. The devices can resolve positions better than 0.5 μm . The resolution is detector / circuit signal to noise ratio dependent.

OSI Optoelectronics manufactures two types of lateral effect PSD's. Duo-Lateral and Tetra-Lateral structures. Both structures are available in one and two-dimensional configurations.

In duo-lateral PSD's, there are two resistive layers, one at the top and the other at the bottom of the photodiode. The photocurrent is divided into two parts in each layer. This structure type can resolve light spot movements of less than 0.5 μm and have very small position detection error, all the way almost to the edge of the active area. They also exhibit excellent position linearity over the entire active area.

The tetra-lateral PSD's, own a single resistive layer, in which the photocurrent is divided into two or four parts for one or two dimensional sensing respectively. These devices exhibit more position non linearity at distances far away from the center, as well as larger position detection errors compared to duo-lateral types.

GLOSSARY OF TERMS:

Position Detection Error (PDE) or Position non-linearity is defined as the geometric variation between the actual position and the measured position of the incident light spot. It is measured over 80% of the sensing length for single dimensional PSD's and 64% of the sensing area for two-dimensional PSD's. For all calculations, the zero point is defined as the electrical center. This is the point at which $I_1 = I_2$. The error is calculated using the following equation:

$$PDE[\mu m] = \left(\frac{I_2 - I_1}{I_2 + I_1} \right) L - X \quad (19)$$

Where I_1 and I_2 are the photocurrents at the ends of the PSD, L is the sensing area half-length in μm , and X is the actual displacement of light spot from the electrical center in μm .

Percentage Position Non-linearity is determined by dividing the position detection error by the total length of the sensing area.

Interelectrode Resistance is the resistance between the two end contacts in one axis, measured with illumination.

Position Detection Thermal Drift is the position drift with change of temperature. It is the change in position divided by the total length. It is defined within 80% of length or 64% of the area for two-dimensional PSD's.

Position Resolution is defined as the minimum detectable displacement of a spot of light on the detector active area. The resolution is limited by the signal to noise ratio of the system. It depends on light intensity, detector noise, and electronics bandwidth. Position resolutions in excess of one part in ten million have been achieved with OSI Optoelectronics lateral effect PSD's.

POSITION CALCULATIONS

Segmented PSD's

Figure 12 shows a typical circuit, used with OSI Optoelectronics segmented photodiodes.

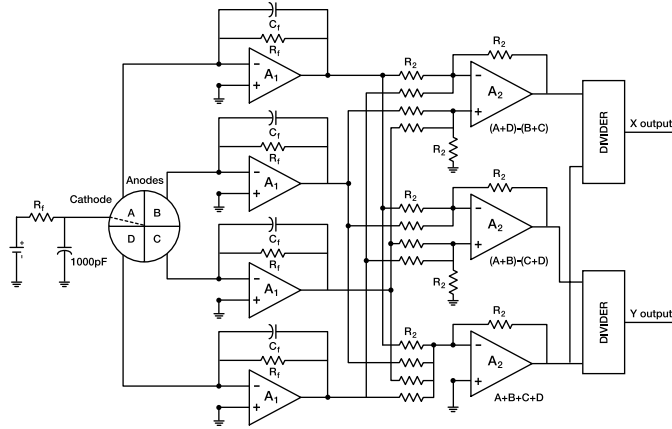


Figure 12. Typical circuit used with segmented photodiodes

The X and Y positions of the light spot with respect to the center on a quadrant photodiode is found by:

$$X = \frac{(A + D) - (B + C)}{A + B + C + D}$$

$$Y = \frac{(A + B) - (C + D)}{A + B + C + D}$$

Where A, B, C, and D are the photocurrents measured by each sector. The recommended components for this circuit are application specific. However, the following components are widely used in most applications:

Amplifiers A ₁ and A ₂ :	OPA-37 or similar
Divider :	AD-534 or similar
R _F and R ₂ :	10 kΩ to 10 MΩ
C _F :	1 / (2πR _F f)

The same circuit can be used for one-dimensional (bi-cell) measurements.

Lateral Effect PSD's

The one dimensional lateral effect measurements are the same for duolateral and tetra-lateral structures, since they both have two contacts on top with a common contact at the bottom. In tetra-lateral devices, however, the common contact is the anode with two cathodes on top, thus making them a positive current generator. In duo-lateral devices there are two anodes on top with a common cathode at the bottom. Figure 13 shows a typical circuit set up used with one-dimensional lateral PSD's.

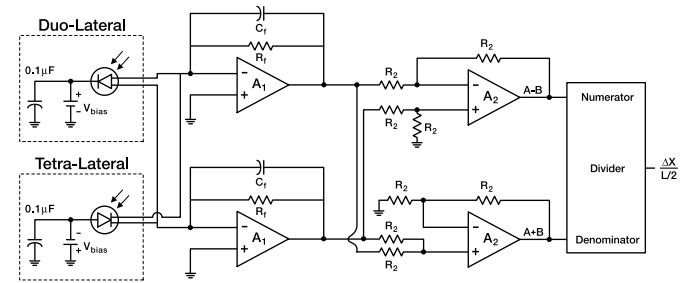


Figure 13. Typical circuit used with one dimensional lateral effect PSD's

In this configuration the outputs from the first stage are summed and subtracted in the second stage and finally divided by the divider in the final stage. The summation, subtraction and the division can be performed by software as well. The position is given as:

$$X = \frac{A - B}{A + B} \quad (21)$$

The same components as the one used in segmented photodiodes can be used with R₂ varying from 1 kΩ to 100 kΩ.

For high-speed applications, the junctions can be reverse biased with a small gain (R_F). For low frequency applications, however, the photodiode can be left unbiased and the gain (R_F), can be as high as 100 MΩ. The feedback capacitor stabilizes the frequency dependence of the gain and can vary from 1 pF to 10 μF. The gain in the first stage amplifier is I_p × R_F, and the gain of the second stage is unity.

(continued)

Two Dimensional Duo-Lateral PSD's

The two dimensional duo-lateral PSD's with two anodes on top and two cathodes on the back surface of the photodiode measure positions in two different directions, respectively. They provide a continuous position reading over the entire active area, with accuracy higher than the tetra-lateral PSD's. **Figure 14** shows a typical circuit for two-dimensional duo-lateral PSD's.

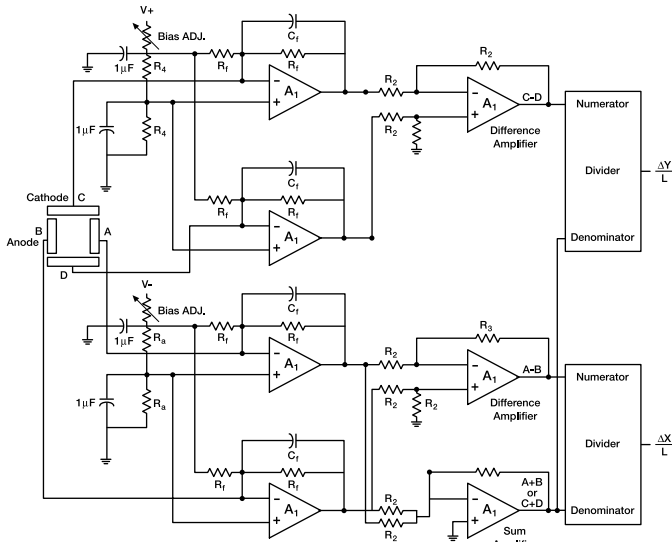


Figure 14. Typical Circuit used with two-dimensional duo-lateral PSD's

For high-speed applications, the cathodes are usually forward biased while the anodes are reverse biased. This extends the bias range that is normally limited by the maximum reverse voltage. The same components as the one-dimensional PSD's are recommended. The output is as follows:

$$X = \frac{A - B}{A + B} \quad (22)$$

$$Y = \frac{C - D}{C + D}$$

Tetra-Lateral PSD's

In a two-dimensional tetra-lateral PSD there are four cathodes and one common anode. Similar to other PSD's, the signals from the detector are converted to voltage in the first stage and then summed and subtracted in the second stage and then finally divided in the final stage. This is shown in **Figure 15**.

For high-speed applications, the anode is reverse biased and the feedback resistor (R_f) shall be chosen small. Additional gain can be achieved by additional stages. The recommended components and the output are similar to two-dimensional duo-lateral devices.

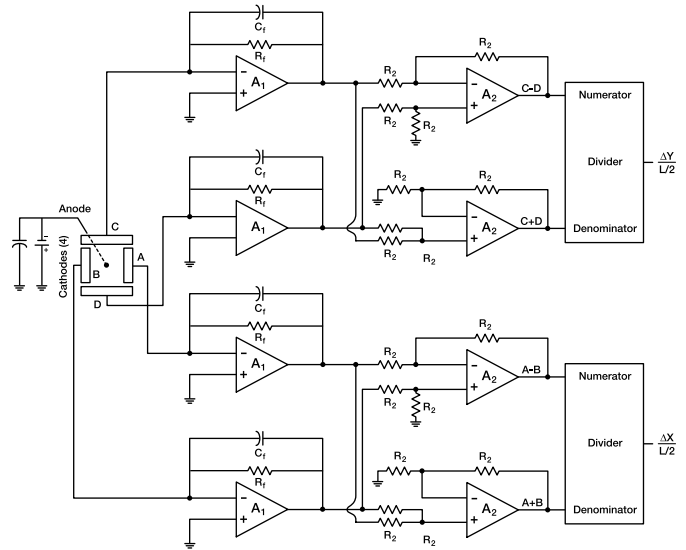


Figure 15. Typical Circuit used with two dimensional tetra-lateral PSD's

The following application notes are available for more technical information about specific uses and applications:

1. Silicon photodiodes come into their own
2. Silicon photodiodes - physics and technology (*)
3. Noise and frequency response of silicon photodiode operational amplifier combination
4. Suitability of silicon photodiodes for laser emission measurements (*)
5. Measuring LED outputs accurately
6. Radiometric and photometric concepts based on measurement techniques
7. Silicon photodiode device with 100% external quantum efficiency
8. Lateral-effect photodiodes (*)
9. Techniques for using the position sensitivity of silicon photodetectors to provide remote machine control
10. Practical electro-optics deflection measurements system
11. Non-contact optical position sensing using silicon photodetectors
12. Continuous position sensing series (LSC, SC)
13. Using photodetectors for position sensing (*)
14. High-precision, wide range, dual axis angle monitoring system
15. Real time biomechanical position sensing based on a lateral effect photodiode (*)
16. A new optical transducer to measure damped harmonic motion
17. Quantum efficiency stability of silicon photodiodes
18. Neutron hardness of photodiodes for use in passive rubidium frequency standards (*)
19. The effect of neutron irradiation on silicon photodiodes
20. Stable, high quantum efficiency, UV-enhanced silicon photodiodes by arsenic diffusion
21. Stable, high quantum efficiency silicon photodiodes for vacuum-UV applications
22. Stability and quantum efficiency performance of silicon photodiode detectors in the far ultraviolet
23. Silicon photodiodes with stable, near-theoretical quantum efficiency in the soft X-ray region

(*) These Files Are Downloadable from the OSI Optoelectronics, Inc. web site.

For any of the above documents, request them by number and write to:



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Recommended Sources For Further Reading:

- Graeme, Jerald, Photodiode Amplifiers, McGraw Hill, New York, 1996
- Dereniak, E.L., and D.G. Crowe, Optical Radiation Detectors, Wiley, New York, 1984.
- Keyes, R.J., Optical and Infrared Detectors, Vol. 19, Topics in Applied Physics, Springer-Verlag, New York, 1980.
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Standard Photodetector Products

Electro-Optical Specifications and Design Notes

Our **strong design** and **creative engineering group**

can provide services from
concept to final manufacture.

In addition to our wide variety of standard photodiodes appearing in the following pages, a majority of OSI Optoelectronics' products include a broad range of custom photodiodes and custom value-added products.

- High Reliability, Military and Aerospace Detectors per Applicable MIL-STDs.
- High Energy Particle Detectors
- Detector / Hybrid Combinations (Thick, Thin and Combifilm Ceramics)
- Detector / Filter Combinations
- Detector / Emitter Combinations
- Detector / PCB Combinations
- Detector / Scintillator Crystal Combinations
- Color Temperature Detectors
- Low Cost Lead Frame Molded Detectors
- Opto Switches and Interrupters
- Detector / Thermo-Electric Cooler Combinations
- Surface Mount Packages
- Custom Position Sensing Detectors
- Multi-Element Array (1D and 2D Configurations)



*Most of our standard catalog products are RoHS Compliant. Please contact us for details.

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